

SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING STRUCTURE

ABSTRACT OF THE DISCLOSURE

5 A semiconductor package with a heat dissipating structure is provided. The heat
dissipating structure includes a flat portion, and a plurality of support portions formed at
edge corners of the flat portion for supporting the flat portion above a chip mounted on a
substrate. The support portions are mounted at predetermined area on the substrate without
interfering with arrangement of the chip and bonding wires that electrically connect the
10 chip to the substrate. The support portions are arranged to form a space embraced by
adjacent supports and the flat portion, so as to allow the bonding wires to pass through the
space to reach area on the substrate outside coverage of the heat dissipating structure;
besides, passive components or other electronic components can be mounted on the
substrate at area within or outside the coverage of the heat dissipating structure, thereby
15 improving flexibility in component arrangement in the semiconductor package.

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